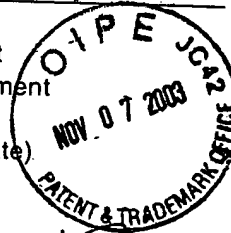


THE U.S. PATENT & TRADEMARK OFFICE  
OFFICIAL MAILROOM STAMP AFFIXED  
HERETO, ACKNOWLEDGES RECEIPT OF:

ENCLOSURES:

- ☐ Application \_\_\_\_\_
- ☐ Specification \_\_\_\_\_ pages
- ☐ Claims \_\_\_\_\_ pages
- ☐ Abstract \_\_\_\_\_ page(s)
- ☐ Drawing Sheets no. \_\_\_\_\_ (F) \_\_\_\_\_ (INF) \_\_\_\_\_
- ☐ Transmittal Letter
- ☒ Check \$ 86.00 No: 15019
- ☐ Declaration/Oath
- ☐ Assignment and Cover Sheet
- ☐ Information Disclosure Statement
- ☐ Response/Amendment
- ☐ Extension of Time (In Duplicate)
- ☐ Small Entity Status
- ☐ Copy of Priority Document
- ☒ Preliminary Amendment B



RE: APPLICATION ATTY/SEC: MJM/smw  
File no: 0553-0166.01  
Applicant: Yamazaki et al

S.N.: 10/629069 Filing Date: July 29, 2003  
Wiring material AND A Semiconductor Device  
Title: HAVING A WIRING USING THE MATERIAL AND  
The Manufacturing Method Thereof

Due date: \_\_\_\_\_ Date Sent: 11/4/03

SEL  
0553-0166.01  
EDM/MJM